

ULTRA LOW LEAKAGE SURFACE MOUNT FAST SWITCHING DIODE

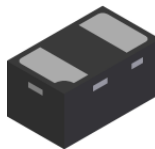
Features

- Ultra-Small, Leadless Surface Mount Package (1.0 x 0.6mm)
- Ultra-Low Profile Package (0.4mm)
- Fast Switching Speed, Fast Reverse Recovery Time
- Ultra-Low Reverse Leakage Current (~ 5nA @ $V_R = 5V$)
- Very Low Capacitance (<1pF @ $V_R=0V$)
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**

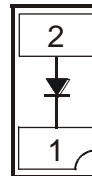
Mechanical Data

- Case: X2-DFN1006-2
- Case Material: Molded Plastic, "Green" Molding Compound; UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: Cathode Bar (See Marking Information)
- Terminals: Finish - NiPdAu over Copper Leadframe; Solderable per MIL-STD-202, Method 208 ④
- Weight: 0.001 grams (Approximate)

X2-DFN1006-2



Bottom View



Device Schematic

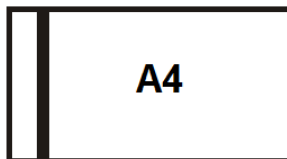
Ordering Information (Note 4)

Part Number	Compliance	Case	Packaging
DLLFSD01LPH4-7B	Standard	X2-DFN1006-2	10,000/Tape & Reel

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.

Marking Information

X2-DFN1006-2



A4 = Product Type Marking Code

Top View
Bar Denotes Cathode Side

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Non-Repetitive Peak Reverse Voltage	V _{RM}	85	V
Peak Repetitive Reverse Voltage	V _{R(RM)}	80	V
Working Peak Reverse Voltage	V _{R(WM)}		
DC Blocking Voltage	V _R		
RMS Reverse Voltage	V _{R(RMS)}	57	V
Forward Continuous Current	I _{FM}	300	mA
Average Rectified Output Current	I _O	100	mA
Non-Repetitive Peak Forward Surge Current @ t = 1.0μs	I _{FSM}	2.0	A

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5)	P _D	350	mW
Thermal Resistance Junction to Ambient Air (Note 5)	R _{θJA}	357	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-65 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 6)	V _{(BR)R}	80	—	—	V	I _R = 100μA
Forward Voltage	V _F	—	0.62	0.7	V	I _F = 1.0mA I _F = 10mA I _F = 100mA
		—	0.74	0.82		
		—	0.94	1.20		
Leakage Current (Note 6)	I _R	—	5	10.0	nA	V _R = 5V V _R = 30V V _R = 80V
		—	—	0.1	μA	
		—	—	0.2	μA	
Total Capacitance	C _T	—	0.5	2.5	pF	V _R = 0, f = 1.0MHz
Reverse Recovery Time	t _{rr}	—	—	4.0	ns	I _F = 10mA, V _R = 6V I _F = I _R = 10mA, I _{rr} = 0.1 x I _R , R _L = 100Ω
		—	—	4.0	ns	

Notes: 5. Part mounted on FR-4 PC board with recommended pad layout, which can be found on our website at <http://www.diodes.com>.
6. Short duration pulse test used to minimize self-heating effect.

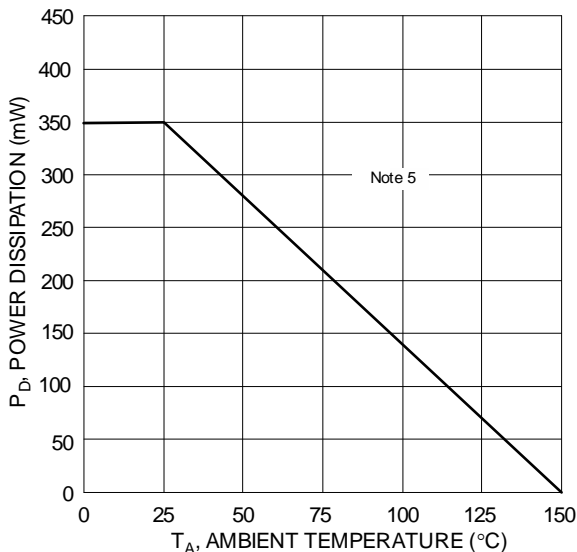


Figure 1 Power Derating Curve, Total Package

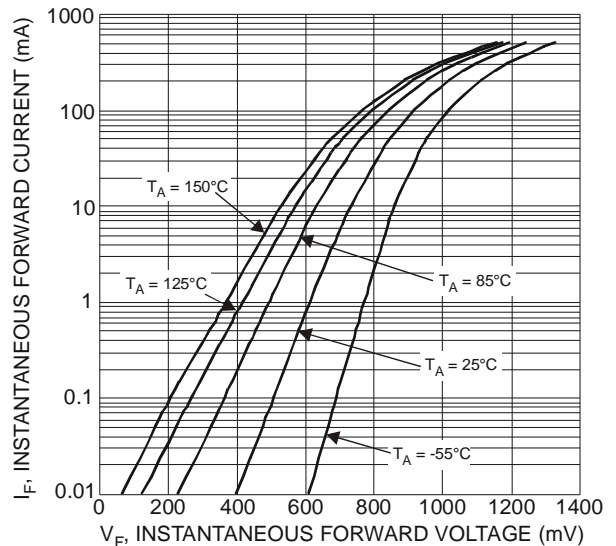


Figure 2 Typical Forward Characteristics

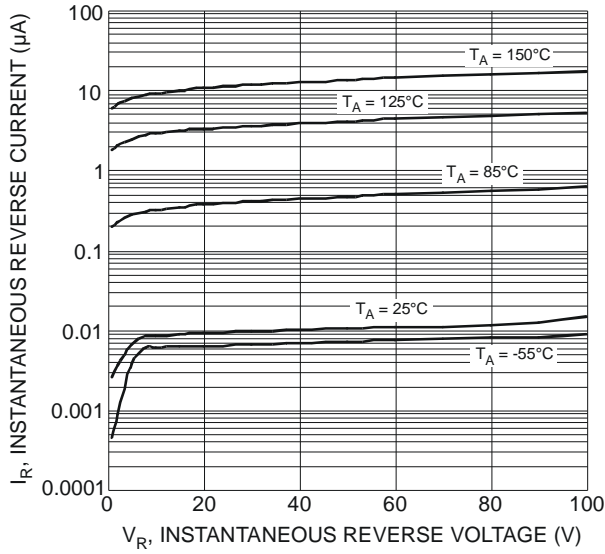


Figure 3 Typical Reverse Characteristics

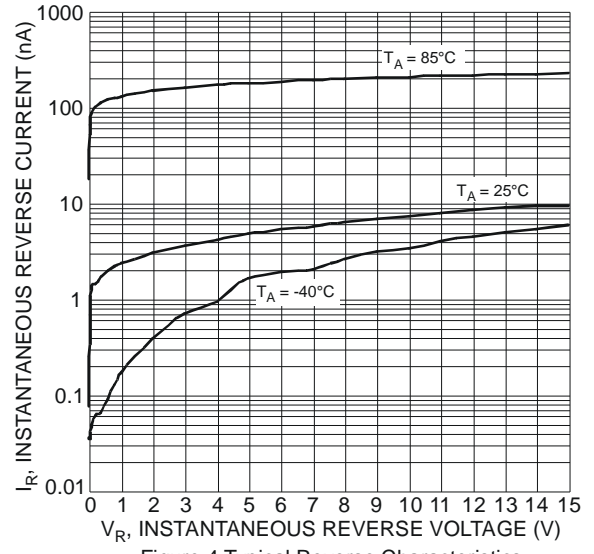


Figure 4 Typical Reverse Characteristics

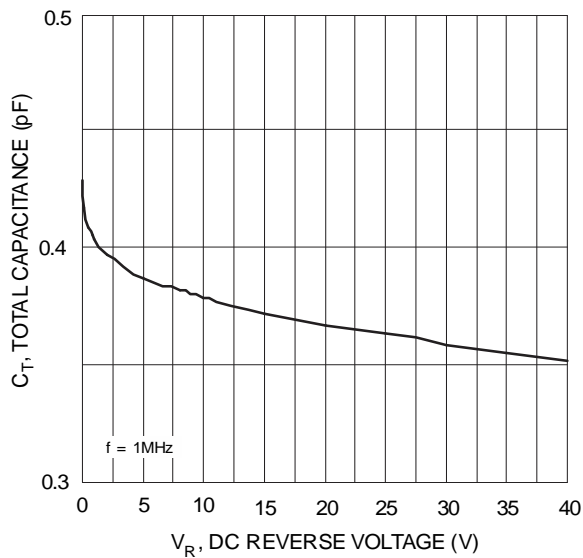
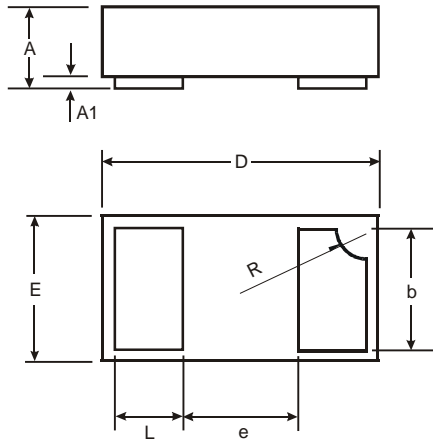


Figure 5 Total Capacitance vs. Reverse Voltage

Package Outline Dimensions

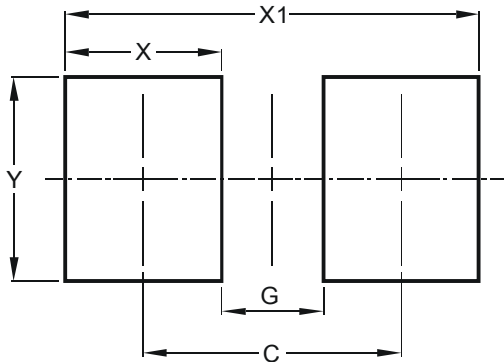
Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for the latest version.



X2-DFN1006-2			
Dim	Min	Max	Typ
A	0.34	0.4	0.37
A1	0	0.05	0.03
b	0.45	0.55	0.50
D	0.95	1.075	1.00
E	0.55	0.675	0.60
e	-	-	0.40
L	0.20	0.30	0.25
R	0.05	0.15	0.10
All Dimensions in mm			

Suggested Pad Layout

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



Dimensions	Value (in mm)
C	0.70
G	0.30
X	0.40
X1	1.10
Y	0.70

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